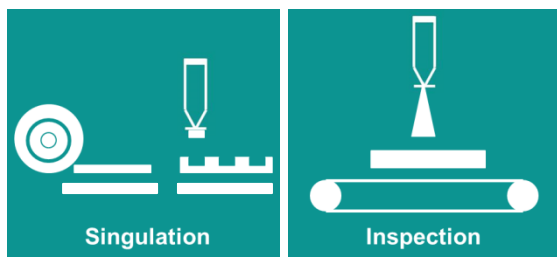


ABC development project



Singulation



Process description.

_Sawing of substrate and inspection and placement of devices



Features.

- _ Magazine load and offloading to Jedec tray
- _ Dual pick & place mechanism
- _ Dual chuck design and dual spindle , one blade / spindle
- _ Vision system with reject units sorting function
- _ Inspection includes (but no limited to): substrate orientation and substrate 2D code reader, device marking quality, broken devices , inked dot , package size X-Y , solder bumps quality ,



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**SUBSTRATE SIZE : 178 x 127 mm
(MAXIMUM)**

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Final Test

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- › Fully testing COOLiR²DIE at high current and voltage presents challenges for a test system and handler
 - Test team chose the LEMSYS test solution
 - Tester capability: 2000A/2000V for static and 2000A/1500V for dynamic testing
- › The handler choice was limited due to the package size and exposed die
- › Multitest selected with vertically docked pick & place handlers
 - A custom manipulator from ESMO was required to provide a working interface on a “headless” LEMSYS tester



LEMSYS Test



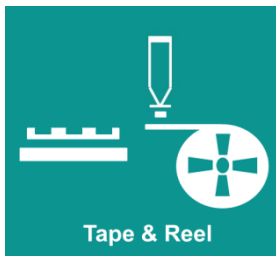
Docked



Undocked – moves on rails



Packing



Process description.

_ Transfer and inspection of singulated devices from Jedec tray to Tape & Reel packing



Features.

- _ 2D inspection system
- _ Loading from Jedec tray or Tape & Reel
- _ Output to Jedec tray or Tape & Reel
- _ Statistics process control tool
- _ 10 head handler for high speed inspection
- _ quadruple pick-and-place head for taping



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